Order this document by
MC68LK332EC16/D

MC68LK332

Technical Supplement

16.78 MHz Electrical Characteristics

Devices in the 68300 Modular Microcontroller Family are built up from a selection of standard functional modules. The MC68LK332 incorporates a central processing unit (CPU32), a system integration module (SIM), a queued serial module (QSM), a time processor unit (TPU), and a 2 K-byte static RAM module with TPU emulation capability (TPURAM). The functionality of the MC68LK332 is enhanced from the MC68L332 to include an operational PLL.

This publication contains a new electrical characteristics appendix for the MC68LK332 to be used in conjunction with the *MC68332 User's Manual* (MC68332UM/AD).

PRELIMINARY

LIST OF ILLUSTRATIONS

LIST OF TABLES

Table 1 Maximum Ratings

Num	Rating	Symbol	Value	Unit
1	Supply Voltage[1, 2, 3]	V_{DD}	– 0.3 to + 6.5	V
2	Input Voltage [1, 2, 3, 4, 5, 7]	V_{IN}	– 0.3 to + 6.5	V
3	Instantaneous Maximum Current Single Pin Limit (all pins)[1, 3, 5, 6]	I_D	25	mA
4	Operating Maximum Current Digital Input Disruptive Current[3, 5, 6, 7, 8] $V_{NEGCLMAP} \cong -0.3$ V $V_{POSCLAMP} \cong V_{DD} + 0.3$	I_{id}	– 500 to 500	µA
5	Operating Temperature Range C Suffix	T_A	T_L to T_H – 40 to 85	°C
6	Storage Temperature Range	T_{stg}	– 55 to 150	°C

NOTES:

1. Permanent damage can occur if maximum ratings are exceeded. Exposure to voltages or currents in excess of recommended values affects device reliability. Device modules may not operate normally while being exposed to electrical extremes.
2. Although sections of the device contain circuitry to protect against damage from high static voltages or electrical fields, take normal precautions to avoid exposure to voltages higher than maximum-rated voltages.
3. This parameter is periodically sampled rather than 100% tested.
4. All pins except TSC.
5. Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, then use the larger of the two values.
6. Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current.
7. All functional non-supply pins are internally clamped to V_{SS}. All functional pins except EXTAL and XFC are internally clamped to V_{DD}.
8. Total input current for all digital input-only and all digital input/output pins must not exceed 10 mA. Exceeding this limit can cause disruption of normal operation.

Table 2 MC68LK332 Typical Ratings

Num	Rating	Symbol	Value	Unit
1	Supply Voltage	V_{DD}	3.3	V
2	Operating Temperature	T_A	25	°C
3	V_{DD} Supply Current RUN LPSTOP, VCO off LPSTOP, External clock, max f_{sys}	I_{DD}	 45 125 1.0	 mA µA mA
4	Clock Synthesizer Operating Voltage	V_{DDSYN}	3.3	V
5	V_{DDSYN} Supply Current VCO on, maximum f_{sys} External Clock, maximum f_{sys} LPSTOP, VCO off V_{DD} powered down	I_{DDSYN}	 1.0 2.0 100 50	 mA mA µA µA
6	RAM Standby Current Normal RAM operation Standby operation	I_{SB}	 3.0 10	 µA µA
7	Power Dissipation	P_D	148.0	mW

Table 3 Thermal Characteristics

Num	Rating	Symbol	Value	Unit
1	Thermal Resistance Plastic 132-Pin Surface Mount Plastic 144-Pin Surface Mount	Θ_{JA}	 38 49	°C/W

The average chip-junction temperature (TJ) in C can be obtained from:

$$T_J = T_A + (P_D \times \Theta_{JA}) \quad (1)$$

where:

T_A = Ambient Temperature, °C
Θ_{JA} = Package Thermal Resistance, Junction-to-Ambient, °C/W
P_D = $P_{INT} + P_{I/O}$
P_{INT} = $I_{DD} \times V_{DD}$, Watts — Chip Internal Power
$P_{I/O}$ = Power Dissipation on Input and Output Pins — User Determined

For most applications $P_{I/O} < P_{INT}$ and can be neglected. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_J + 273°C) \quad (2)$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273°C) + \Theta_{JA} \times P_D^2 \quad (3)$$

where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving equations (1) and (2) iteratively for any value of T_A.

Table 4 Clock Control Timing

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	PLL Reference Frequency Range	f_{ref}	20	50	kHz
2	System Frequency[1] On-Chip PLL System Frequency External Clock Operation	f_{sys}	$4(f_{ref})$ dc	16.78 16.78	MHz
3	PLL Lock Time[2, 3, 4, 5]	t_{lpll}	—	20	ms
4	VCO Frequency[6]	f_{VCO}	—	2 (f_{sys} max)	MHz
5	CLKOUT Jitter[2, 3, 4, 7] Short term (5 µs interval) Long term (500 µs interval)	J_{clk}	–1.0 –0.5	1.0 0.5	%

NOTES:

1. All internal registers retain data at 0 Hz.
2. This parameter is periodically sampled rather than 100% tested.
3. Assumes that a low-leakage external filter network is used to condition clock synthesizer input voltage. Total external resistance from the XFC pin due to external leakage must be greater than 15 MΩ to guarantee this specification. Filter network geometry can vary depending upon operating environment.
4. Proper layout procedures must be followed to achieve specifications.
5. Assumes that stable V_{DDSYN} is applied, and that the crystal oscillator is stable. Lock time is measured from the time V_{DD} and V_{DDSYN} are valid until $\overline{\text{RESET}}$ is released. This specification also applies to the period required for PLL lock after changing the W and Y frequency control bits in the synthesizer control register (SYNCR) while the PLL is running, and to the period required for the clock to lock after LPSTOP.
6. Internal VCO frequency (f_{VCO}) is determined by SYNCR W and Y bit values. The SYNCR X bit controls a divide-by-two circuit that is not in the synthesizer feedback loop. When X = 0, the divider is enabled, and $f_{sys} = f_{VCO} \div 4$. When X = 1, the divider is disabled, and $f_{sys} = f_{VCO} \div 2$. X must equal one when operating at maximum specified f_{sys}.
7. Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum f_{sys}. Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the PLL circuitry via V_{DDSYN} and V_{SS} and variation in crystal oscillator frequency increase the J_{clk} percentage for a given interval. When jitter is a critical constraint on control system operation, this parameter should be measured during functional testing of the final system.

Table 5 16.78 MHz DC Characteristics

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	Input High Voltage	V_{IH}	0.7 (V_{DD})	V_{DD} + 0.3	V
2	Input Low Voltage	V_{IL}	V_{SS} – 0.3	0.2 (V_{DD})	V
3	Input Hysteresis[1]	V_{HYS}	0.5	—	V
4	Input Leakage Current [2] $V_{in} = V_{DD}$ or V_{SS} Input-only pins	I_{in}	–2.5	2.5	µA
5	High Impedance (Off-State) Leakage Current[2] $V_{in} = V_{DD}$ or V_{SS} All input/output and output pins	I_{OZ}	–2.5	2.5	µA
6	CMOS Output High Voltage[2, 3] I_{OH} = –10.0 µA Group 1, 2, 4 input/output and output pins	V_{OH}	V_{DD} –0.2	—	V
7	CMOS Output Low Voltage[2] I_{OL} = 10.0 µA Group 1, 2, 4 input/output and output pins	V_{OL}	—	0.2	V
8	TTL Compatible Output High Voltage[2, 3] I_{OH} = –0.4 mA Group 1, 2, 4 input/output and output pins	V_{OH}	V_{DD} –0.5	—	V
9	TTL Compatible Output Low Voltage[2] I_{OL} = 0.8 mA Group 1 I/O pins, CLKOUT, FREEZE/QUOT, $\overline{IPIPE}$/DSO I_{OL} = 2.6 mA Group 2 and Group 4 I/O pins, $\overline{CSBOOT}$, $\overline{BG}$/$\overline{CS1}$ I_{OL} = 6.0 mA Group 3	V_{OL}	— — —	0.4 0.4 0.4	V
10	Three State Control Input High Voltage	V_{IHTSC}	2.4 (V_{DD})	9.1	V
11	Data Bus Mode Select Pull-up Current [4] $V_{in} = V_{IL}$ $V_{in} = V_{IH}$	I_{MSP}	— –8	–95 —	µA
12	V_{DD} Supply Current[5] Run LPSTOP, external clock input frequency = max f_{sys} Run, emulation mode LPSTOP, crystal reference, VCO off (STSIM = 0)	I_{DD}	— — — —	56 2 59 350	mA mA mA µA
13	Clock Synthesizer Operating Voltage	V_{DDSYN}	3.0	3.6	V
14	V_{DDSYN} Supply Current External clock, maximum f_{sys} Crystal reference, VCO on, maximum f_{sys} LPSTOP, crystal reference, VCO off, (STSIM = 0) V_{DD} powered down	I_{DDSYN}	— — — —	3 1 150 100	mA mA µA µA
15	RAM Standby Voltage Specified V_{DD} applied $V_{DD} = V_{SS}$	V_{SB}	0.0 2.7	V_{DD} 3.6	V

Table 5 16.78 MHz DC Characteristics (Continued)

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
16	RAM Standby Current[6, 7] Normal RAM operation $V_{DD} > V_{SB} - 0.5$ V Transient condition $V_{SB} - 0.5$ V $\geq V_{DD} \geq V_{SS} + 0.5$ V Standby operation $V_{DD} < V_{SS} + 0.5$ V	I_{SB}	— — —	10 3 50	µA mA µA
17	Power Dissipation[8]	P_D	—	212	mW
18	Input Capacitance[2, 9] All input-only pins All input/output pins	C_{in}	— —	10 20	pF
19	Load Capacitance[2] Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, IPIPE/DSO Group 2 I/O Pins and CSBOOT, BG/CS1 Group 3 I/O Pins Group 4 I/O Pins	C_L	— — — —	90 100 100 100	pF

NOTES:

1. Applies to:
   QSM pins
   IRQ[7:1], RESET, EXTAL, TSC, RMC, BKPT/DSCLK, IFETCH/DSI
2. Input-Only Pins: TSC, BKPT/DSCLK, RXD
   Output-Only Pins: CSBOOT, BG/CS1, CLKOUT, FREEZE/QUOT, IPIPE/DSO
   Input/Output Pins:
   Group 1: DATA[15:0], IFETCH/DSI
   Group 2: ADDR[23:19]/CS[10:6], FC[2:0]/CS[5:3], DSACK[1:0], AVEC, RMC, DS, AS, SIZ[1:0]
   IRQ[7:1], MODCLK, ADDR[18:0], R/W, BERR, BR/CS0, BGACK/CS2, PCS[3:1], PCS0/SS, TXD
   Group 3: HALT, RESET
   Group 4: MISO, MOSI, SCK
3. Does not apply to HALT and RESET because they are open drain pins.
   Does not apply to Port QS[7:0] (TXD, PCS[3:1], PCS0/SS, SCK, MOSI, MISO) in wired-OR mode.
4. Current measured at maximum system clock frequency.
5. Total operating current is the sum of the appropriate V_{DD} supply and V_{DDSYN} supply current.
6. When V_{SB} is more than 0.3V greater than V_{DD}, current flows between the V_{STBY} and V_{DD} pins, which causes standby current to increase toward the maximum condition specification. System noise on the V_{DD} and V_{STBY} pin can contribute to this condition.
7. The SRAM module will not switch into standby mode as long as V_{SB} does not exceed V_{DD} by more than 0.5 volts. The SRAM array cannot be accessed while the module is in standby mode.
8. Power dissipation measured at specified system clock frequency, all modules active. Power dissipation can be calculated using the expression:
   $$P_D = 3.6V\ (I_{DDSYN} + I_{DD})$$
   I_{DD} includes supply currents for all device modules powered by V_{DD} pins
9. Input capacitance is periodically sampled rather than 100% tested.

Table 6 16.78 MHz AC Timing

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H [1]

Num	Characteristic	Symbol	Min	Max	Unit
F1	Frequency of Operation	f	DC	16.78	MHz
1	Clock Period	t_{cyc}	59.6	—	ns
1A	ECLK Period	t_{Ecyc}	476	—	ns
1B	External Clock Input Period[2]	t_{Xcyc}	59.6	—	ns
2, 3	Clock Pulse Width	t_{CW}	24	—	ns
2A, 3A	ECLK Pulse Width	t_{ECW}	236	—	ns
2B, 3B	External Clock Input High/Low Time[2]	t_{XCHL}	29.8	—	ns
4, 5	CLKOUT Rise and Fall Time	t_{Crf}	—	7	ns
4A, 5A	Rise and Fall Time (All outputs except CLKOUT)	t_{rf}	—	8	ns
4B, 5B	External Clock Input Rise and Fall Time	t_{XCrf}	—	4	ns
6	Clock High to ADDR, FC, $\overline{RMC}$, SIZ Valid	t_{CHAV}	0	29	ns
7	Clock High to ADDR, Data, FC, $\overline{RMC}$,SIZ High Impedance	t_{CHAZx}	0	59	ns
8	Clock High to ADDR, FC, $\overline{RMC}$, SIZ Invalid	t_{CHAZn}	0	—	ns
9	Clock Low to $\overline{AS}$, $\overline{DS}$, $\overline{CS}$ Asserted	t_{CLSA}	0	25	ns
9A	$\overline{AS}$ to $\overline{DS}$ or $\overline{CS}$ Asserted (Read)[3]	t_{STSA}	-15	15	ns
9C	Clock Low to $\overline{IFETCH}$, $\overline{IPIPE}$ Asserted	t_{CLIA}	2	22	ns
11	ADDR, FC, $\overline{RMC}$, SIZ Valid to $\overline{AS}$, $\overline{CS}$, (and $\overline{DS}$ Read) Asserted	t_{AVSA}	15	—	ns
12	Clock Low to $\overline{AS}$, $\overline{DS}$, $\overline{CS}$ Negated	t_{CLSN}	2	29	ns
12A	Clock Low to $\overline{IFETCH}$, $\overline{IPIPE}$ Negated	t_{CLIN}	2	29	ns
13	$\overline{AS}$, $\overline{DS}$, $\overline{CS}$ Negated to ADDR, FC, SIZ Invalid (Address Hold)	t_{SNAI}	15	—	ns
14	$\overline{AS}$, $\overline{CS}$ (and $\overline{DS}$ Read) Width Asserted	t_{SWA}	100	—	ns
14A	$\overline{DS}$, $\overline{CS}$ Width Asserted (Write)	t_{SWAW}	45	—	ns
14B	$\overline{AS}$, $\overline{CS}$ (and $\overline{DS}$ Read) Width Asserted (Fast Cycle)	t_{SWDW}	40	—	ns
15	$\overline{AS}$, $\overline{DS}$, $\overline{CS}$ Width Negated[4]	t_{SN}	40	—	ns
16	Clock High to $\overline{AS}$, $\overline{DS}$, R/$\overline{W}$ High Impedance	t_{CHSZ}	—	59	ns
17	$\overline{AS}$, $\overline{DS}$, $\overline{CS}$ Negated to R/$\overline{W}$ High	t_{SNRN}	15	—	ns
18	Clock High to R/$\overline{W}$ High	t_{CHRH}	0	29	ns
20	Clock High to R/$\overline{W}$ Low	t_{CHRL}	0	29	ns
21	R/$\overline{W}$ High to $\overline{AS}$, $\overline{CS}$ Asserted	t_{RAAA}	15	—	ns
22	R/$\overline{W}$ Low to $\overline{DS}$, $\overline{CS}$ Asserted (Write)	t_{RASA}	70	—	ns
23	Clock High to Data Out Valid	t_{CHDO}	—	29	ns

Table 6 16.78 MHz AC Timing (Continued)

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H [1]

Num	Characteristic	Symbol	Min	Max	Unit
24	Data Out Valid to Negating Edge of $\overline{AS}$, $\overline{CS}$ (Fast Write Cycle)	t_{DVASN}	15	—	ns
25	$\overline{DS}$, $\overline{CS}$ Negated to Data Out Invalid (Data Out Hold)	t_{SNDOI}	15	—	ns
26	Data Out Valid to $\overline{DS}$, $\overline{CS}$ Asserted (Write)	t_{DVSA}	15	—	ns
27	Data In Valid to Clock Low (Data Setup)	t_{DICL}	5	—	ns
27A	Late $\overline{BERR}$, $\overline{HALT}$ Asserted to Clock Low (Setup Time)	t_{BELCL}	20	—	ns
28	$\overline{AS}$, $\overline{DS}$ Negated to $\overline{DSACK[1:0]}$, $\overline{BERR}$, $\overline{HALT}$, $\overline{AVEC}$ Negated	t_{SNDN}	0	80	ns
29	$\overline{DS}$, $\overline{CS}$ Negated to Data In Invalid (Data In Hold)[5]	t_{SNDI}	0	—	ns
29A	$\overline{DS}$, $\overline{CS}$ Negated to Data In High Impedance[5, 6]	t_{SHDI}	—	55	ns
30	CLKOUT Low to Data In Invalid (Fast Cycle Hold)[5]	t_{CLDI}	10	—	ns
30A	CLKOUT Low to Data In High Impedance[5]	t_{CLDH}	—	90	ns
31	$\overline{DSACK[1:0]}$ Asserted to Data In Valid[7]	t_{DADI}	—	50	ns
33	Clock Low to $\overline{BG}$ Asserted/Negated	t_{CLBAN}	—	29	ns
35	$\overline{BR}$ Asserted to $\overline{BG}$ Asserted ($\overline{RMC}$ not Asserted)[8]	t_{BRAGA}	1	—	t_{cyc}
37	$\overline{BGACK}$ Asserted to $\overline{BG}$ Negated	t_{GAGN}	1	2	t_{cyc}
39	$\overline{BG}$ Width Negated	t_{GH}	2	—	t_{cyc}
39A	$\overline{BG}$ Width Asserted	t_{GA}	1	—	t_{cyc}
46	R/$\overline{W}$ Width Asserted (Write or Read)	t_{RWA}	150	—	ns
46A	R/$\overline{W}$ Width Asserted (Fast Write or Read Cycle)	t_{RWAS}	90	—	ns
47A	Asynchronous Input Setup Time $\overline{BR}$, $\overline{BGACK}$, $\overline{DSACK[1:0]}$, $\overline{BERR}$, $\overline{AVEC}$, $\overline{HALT}$	t_{AIST}	5	—	ns
47B	Asynchronous Input Hold Time	t_{AIHT}	15	—	ns
48	$\overline{DSACK[1:0]}$ Asserted to $\overline{BERR}$, $\overline{HALT}$ Asserted[9]	t_{DABA}	—	30	ns
53	Data Out Hold from Clock High	t_{DOCH}	0	—	ns
54	Clock High to Data Out High Impedance	t_{CHDH}	—	28	ns
55	R/$\overline{W}$ Asserted to Data Bus Impedance Change	t_{RADC}	40	—	ns
70	Clock Low to Data Bus Driven (Show Cycle)	t_{SCLDD}	0	29	ns
71	Data Setup Time to Clock Low (Show Cycle)	t_{SCLDS}	15	—	ns
72	Data Hold from Clock Low (Show Cycle)	t_{SCLDH}	10	—	ns
73	$\overline{BKPT}$ Input Setup Time	t_{BKST}	15	—	ns
74	$\overline{BKPT}$ Input Hold Time	t_{BKHT}	10	—	ns
75	Mode Select Setup Time	t_{MSS}	20	—	t_{cyc}
76	Mode Select Hold Time	t_{MSH}	0	—	ns

Table 6 16.78 MHz AC Timing (Continued)

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H[1]

Num	Characteristic	Symbol	Min	Max	Unit
77	$\overline{\text{RESET}}$ Assertion Time[10]	t_{RSTA}	4	—	t_{cyc}
78	$\overline{\text{RESET}}$ Rise Time[11, 12]	t_{RSTR}	—	10	t_{cyc}

NOTES:

1. All AC timing is shown with respect to 2.0 V to 0.8 V levels unless otherwise noted.
2. When an external clock is used, minimum high and low times are based on a 50% duty cycle. The minimum allowable t_{Xcyc} period is reduced when the duty cycle of the external clock varies. The relationship between external clock input duty cycle and minimum t_{Xcyc} is expressed:
   Minimum t_{Xcyc} period = minimum t_{XCHL} / (50% – external clock input duty cycle tolerance).
3. Specification 9A is the worst-case skew between $\overline{\text{AS}}$ and $\overline{\text{DS}}$ or $\overline{\text{CS}}$. The amount of skew depends on the relative loading of these signals. When loads are kept within specified limits, skew will not cause $\overline{\text{AS}}$ and $\overline{\text{DS}}$ to fall outside the limits shown in specification 9.
4. If multiple chip-selects are used, $\overline{\text{CS}}$ width negated (specification 15) applies to the time from the negation of a heavily loaded chip-select to the assertion of a lightly loaded chip select. The $\overline{\text{CS}}$ width negated specification between multiple chip-selects does not apply to chip selects being used for synchronous ECLK cycles.
5. Hold times are specified with respect to $\overline{\text{DS}}$ or $\overline{\text{CS}}$ on asynchronous reads and with respect to CLKOUT on fast cycle reads. The user is free to use either hold time.
6. Maximum value is equal to (t_{cyc} / 2) + 25 ns.
7. If the asynchronous setup time (specification 47A) requirements are satisfied, the $\overline{\text{DSACK[1:0]}}$ low to data setup time (specification 31) and $\overline{\text{DSACK[1:0]}}$ low to $\overline{\text{BERR}}$ low setup time (specification 48) can be ignored. The data must only satisfy the data-in to clock low setup time (specification 27) for the following clock cycle. $\overline{\text{BERR}}$ must satisfy only the late $\overline{\text{BERR}}$ low to clock low setup time (specification 27A) for the following clock cycle.
8. To ensure coherency during every operand transfer, $\overline{\text{BG}}$ is not asserted in response to $\overline{\text{BR}}$ until after all cycles of the current operand transfer are complete.
9. In the absence of $\overline{\text{DSACK[1:0]}}$, $\overline{\text{BERR}}$ is an asynchronous input using the asynchronous setup time (specification 47A).
10. After external $\overline{\text{RESET}}$ negation is detected, a short transition period (approximately 2) t_{cyc} elapses, then the SIM drives $\overline{\text{RESET}}$ low for 512 t_{cyc}.
11. External assertion of the $\overline{\text{RESET}}$ input can overlap internally-generated resets. To insure that an external reset is recognized in all cases, $\overline{\text{RESET}}$ must be asserted for at least 590 CLKOUT cycles.
12. External logic must pull $\overline{\text{RESET}}$ high during this period in order for normal MCU operation to begin.

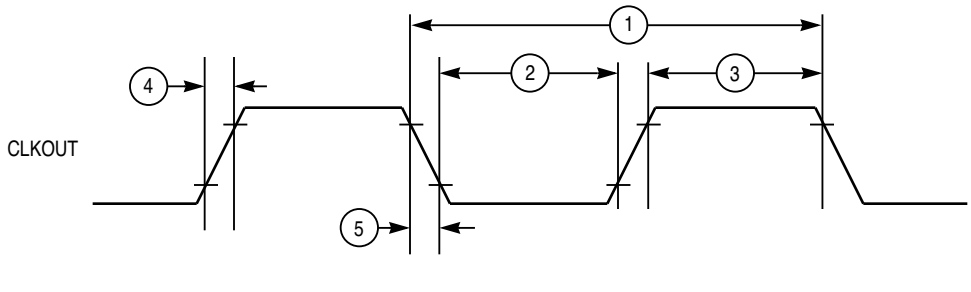
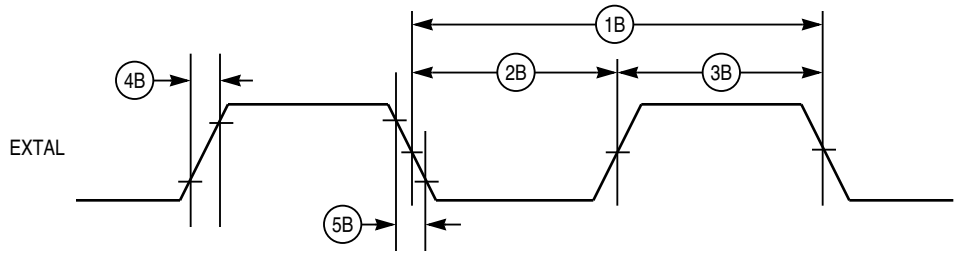


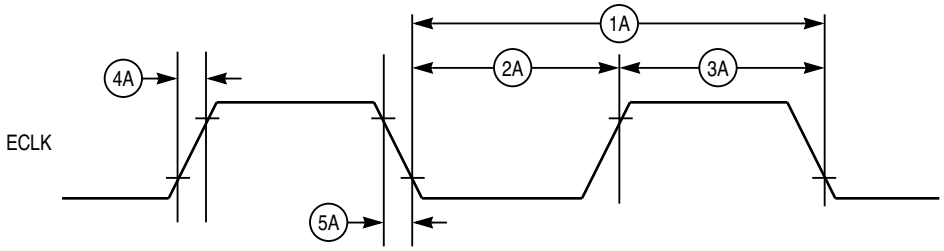
Figure 1 CLKOUT Output Timing Diagram



NOTE: PULSE WIDTH SHOWN WITH RESPECT TO 50% V_{DD}.

68300 EXT CLK INPUT TIM

Figure 2 External Clock Input Timing Diagram



68300 ECLK OUTPUT TIM

Figure 3 ECLK Output Timing Diagram

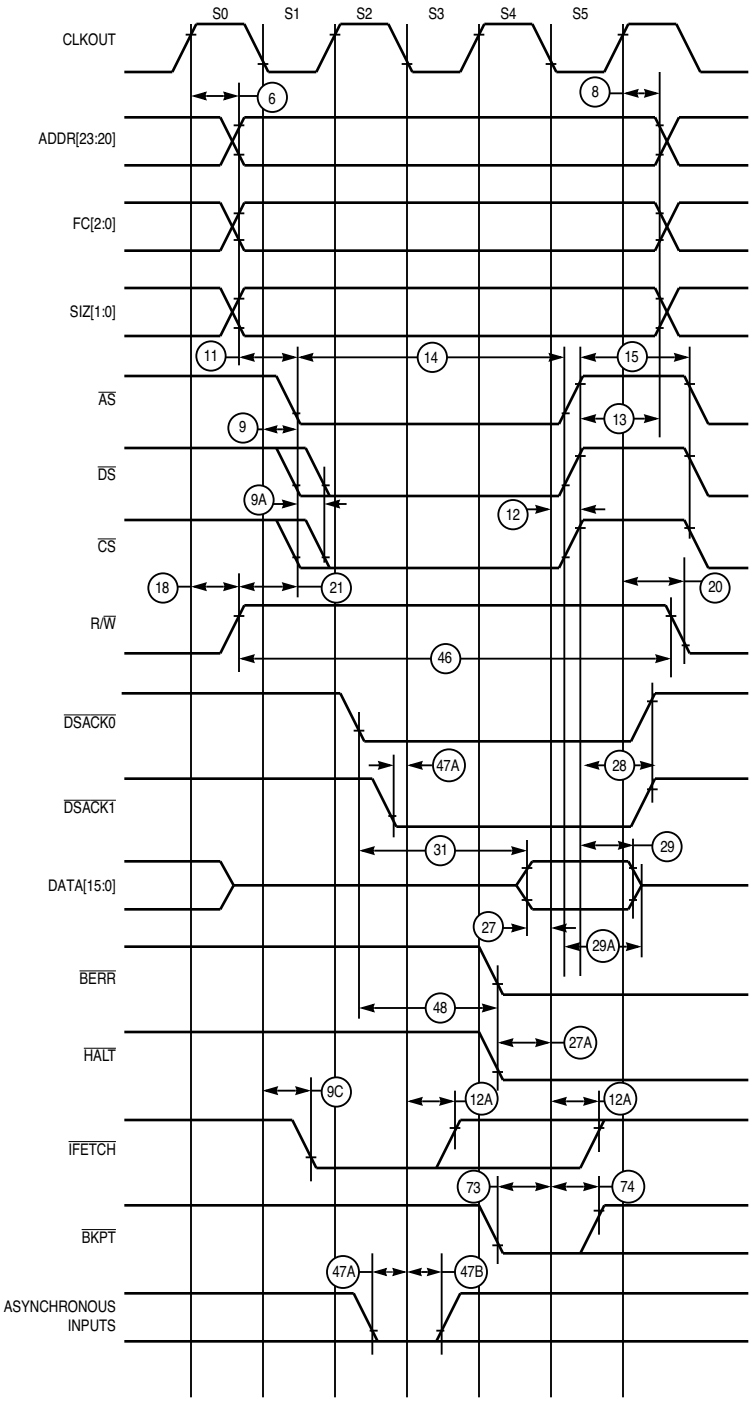


Figure 4 Read Cycle Timing Diagram

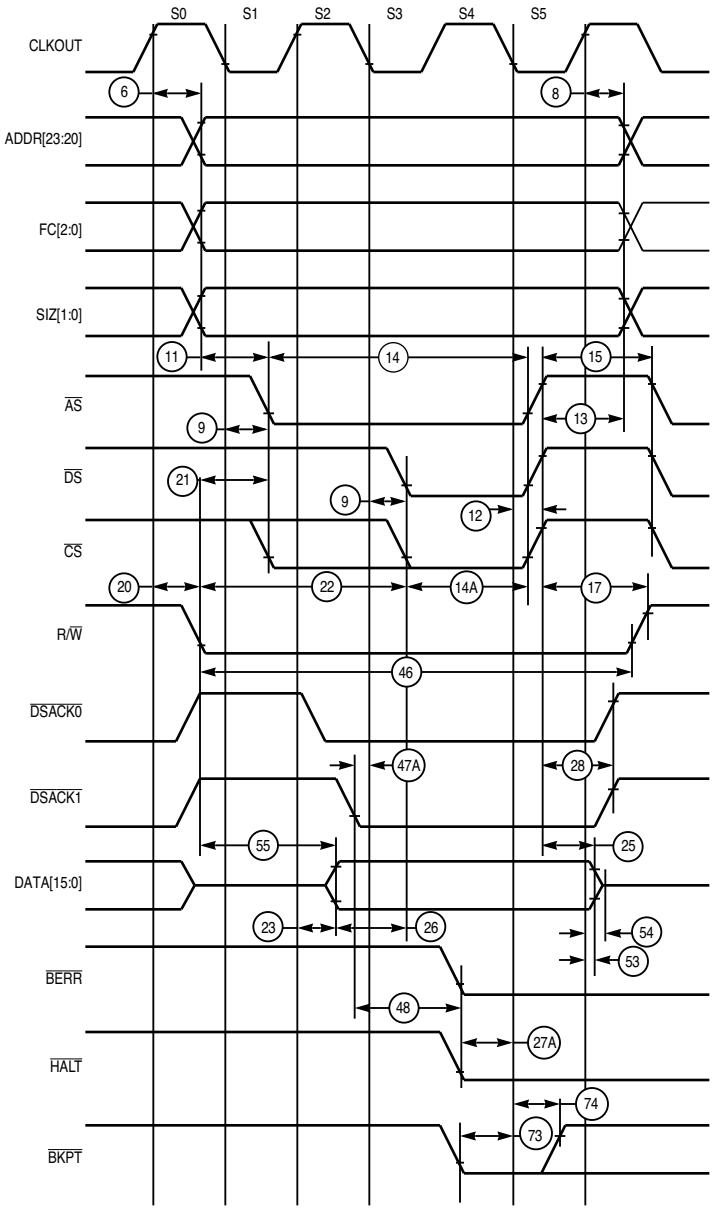


Figure 5 Write Cycle Timing Diagram

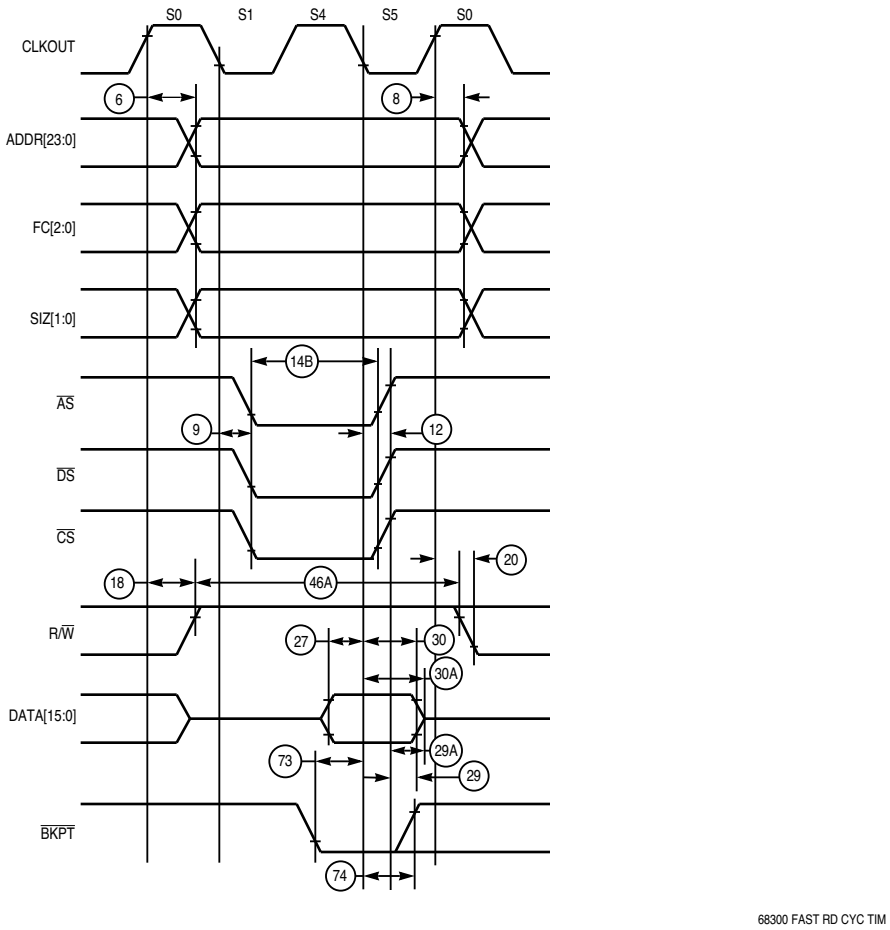


Figure 6 Fast Termination Read Cycle Timing Diagram

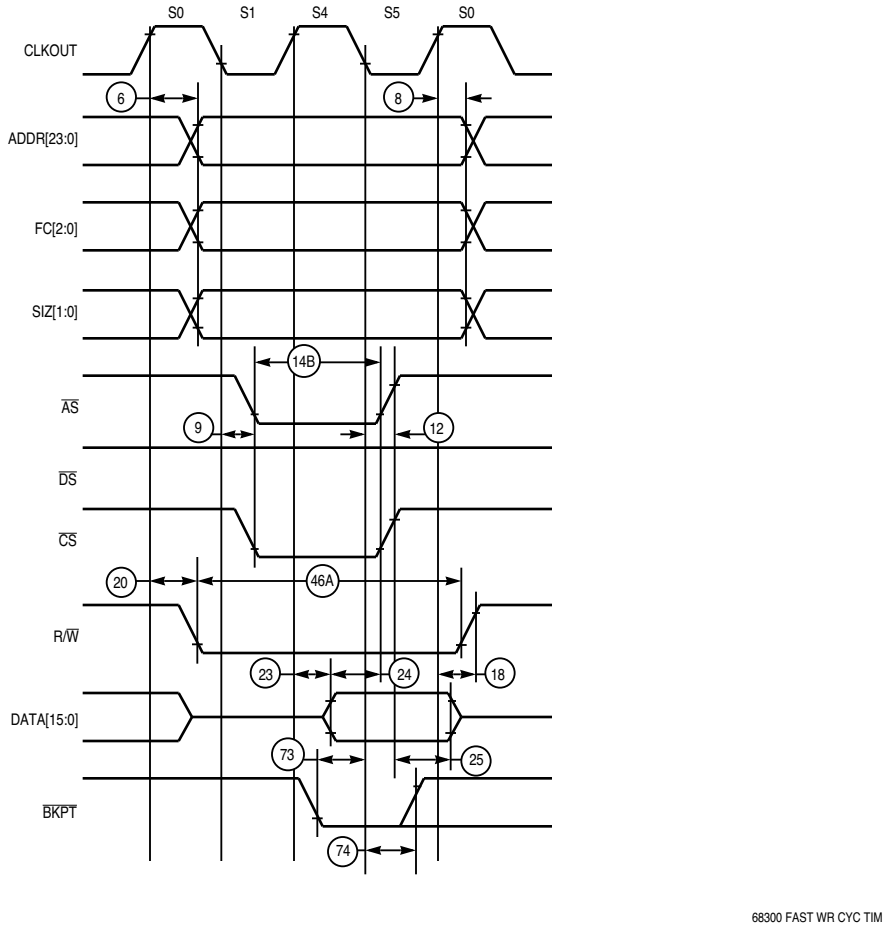


Figure 7 Fast Termination Write Cycle Timing Diagram

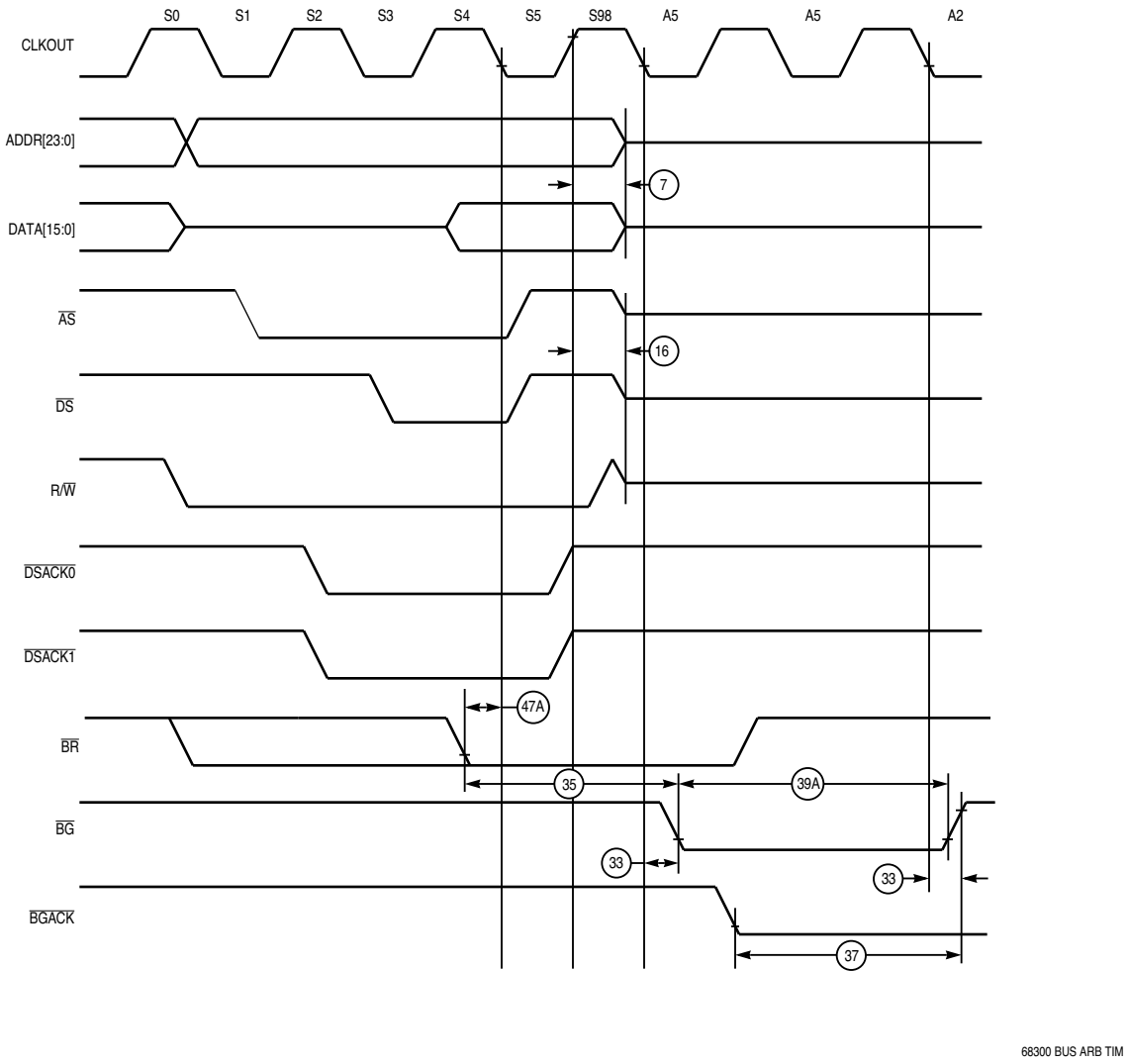


Figure 8 Bus Arbitration Timing Diagram — Active Bus Case

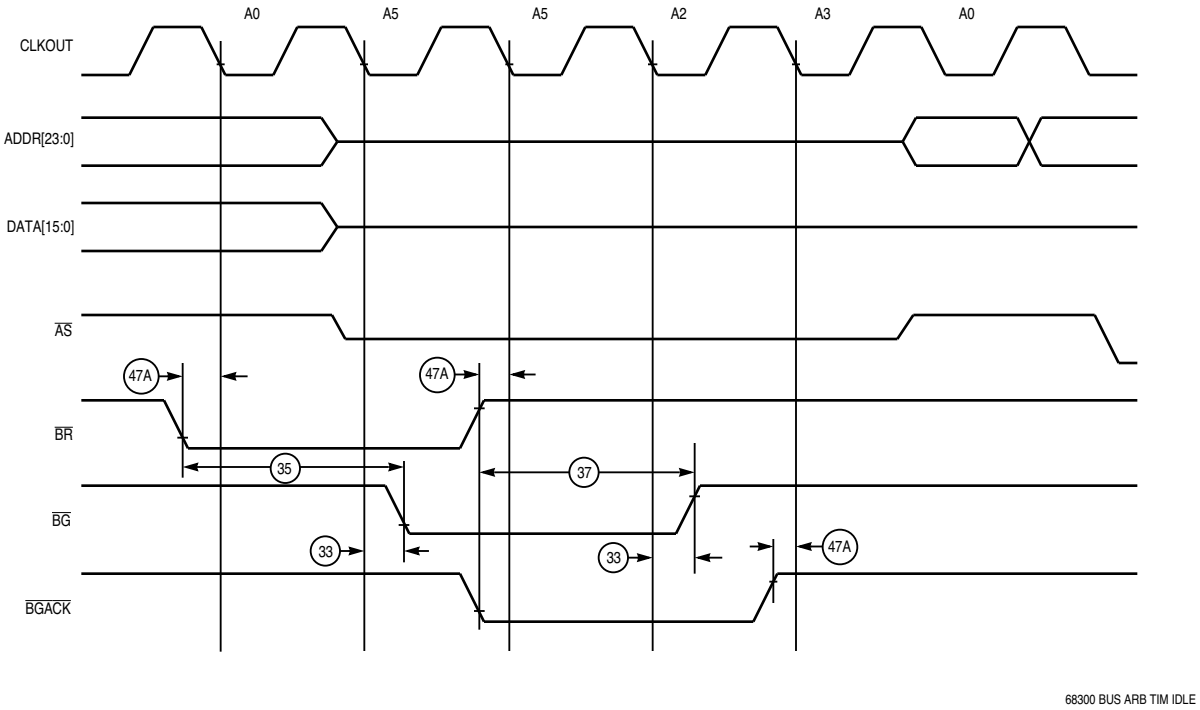
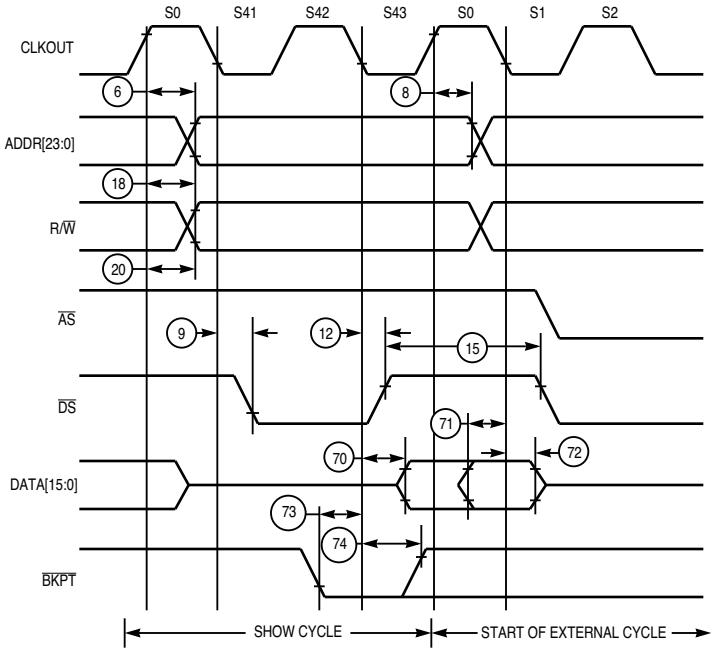


Figure 9 Bus Arbitration Timing Diagram — Idle Bus Case



NOTE:
SHOW CYCLES CAN STRETCH DURING CLOCK PHASE S42 WHEN BUS ACCESSES TAKE LONGER THAN TWO CYCLES DUE TO IMB MODULE WAIT-STATE INSERTION.

68300 SHW CYC TIM

Figure 10 Show Cycle Timing Diagram

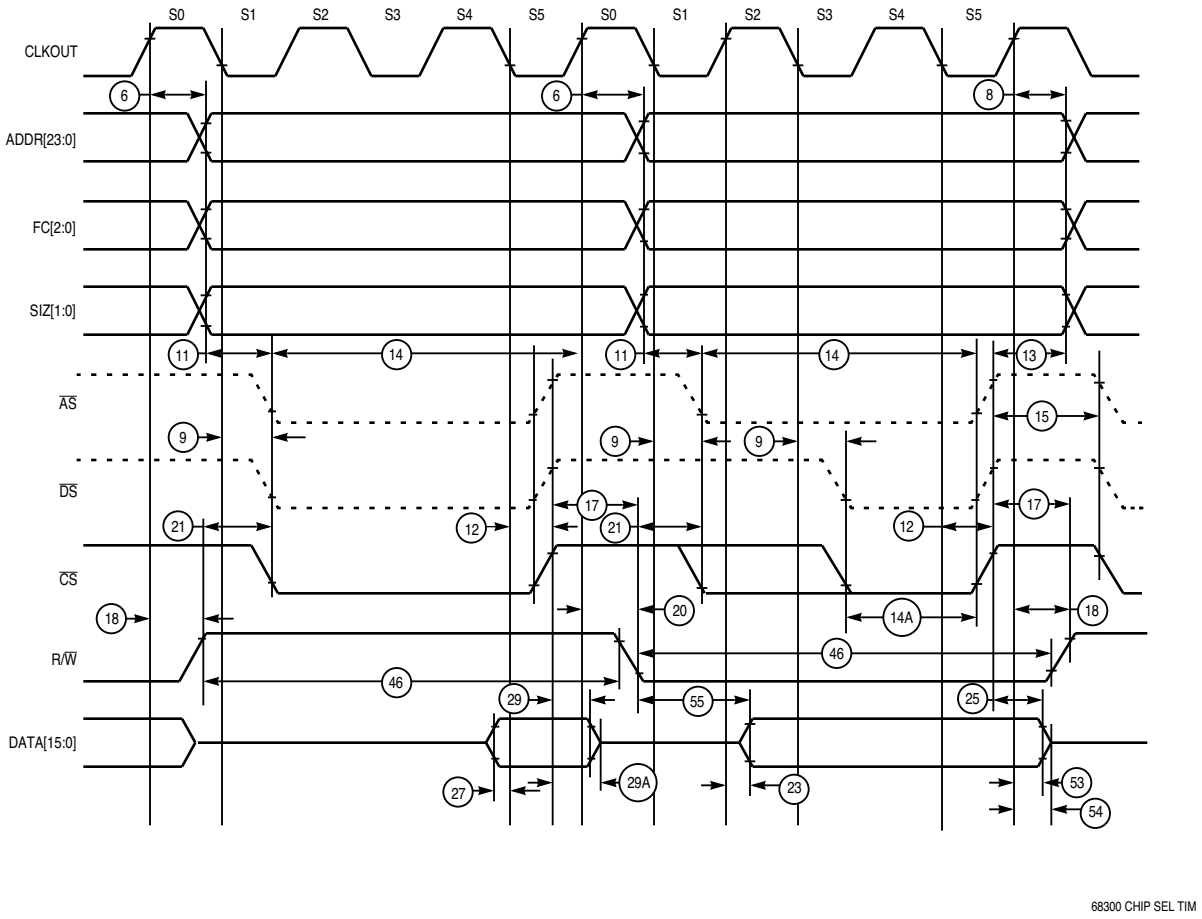


Figure 11 Chip-Select Timing Diagram

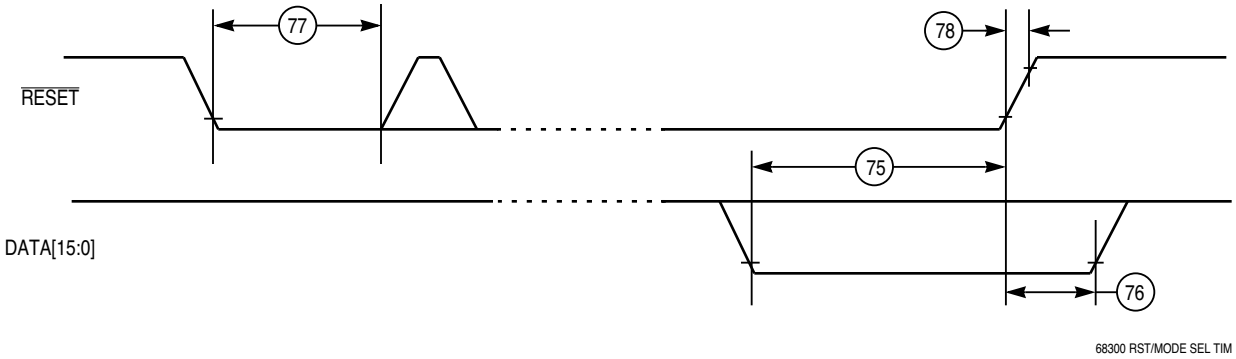


Figure 12 Reset and Mode Select Timing Diagram

Table 7 Background Debugging Mode Timing

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)[1]

Num	Characteristic	Symbol	Min	Max	Unit
B0	DSI Input Setup Time	t_{DSISU}	15	—	ns
B1	DSI Input Hold Time	t_{DSIH}	10	—	ns
B2	DSCLK Setup Time	t_{DSCSU}	15	—	ns
B3	DSCLK Hold Time	t_{DSCH}	10	—	ns
B4	DSO Delay Time	t_{DSOD}	—	25	ns
B5	DSCLK Cycle Time	t_{DSCCYC}	2	—	t_{cyc}
B6	CLKOUT Low to FREEZE Asserted/Negated	t_{FRZAN}	—	50	ns
B7	CLKOUT High to $\overline{\text{IFETCH}}$ High Impedance	t_{IPZ}	—	50	ns
B8	CLKOUT High to $\overline{\text{IFETCH}}$ Valid	t_{IP}	—	50	ns
B9	DSCLK Low Time	t_{DSCLO}	1	—	t_{cyc}

NOTES:
1. All AC timing is shown with respect to 20% V_{DD} and 70% V_{DD} levels unless otherwise noted.

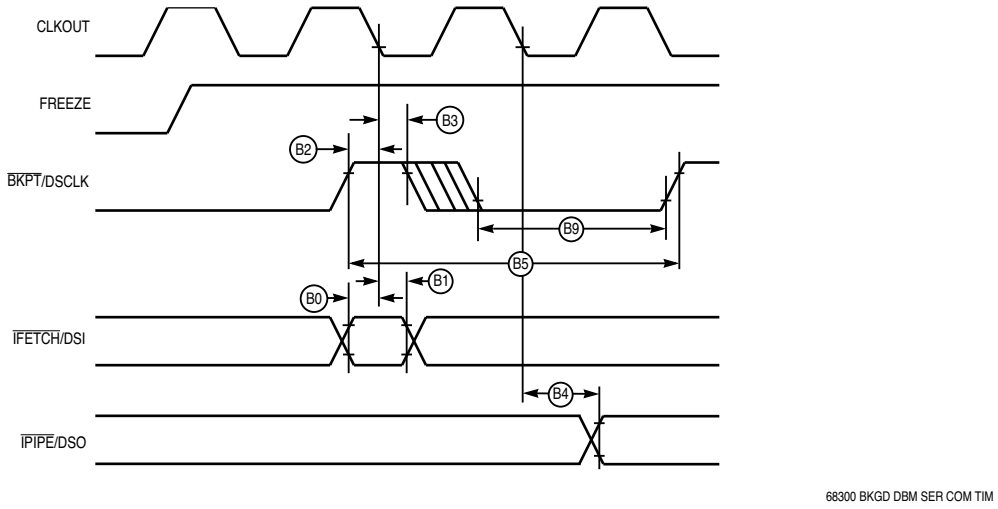


Figure 13 BDM Serial Communication Timing Diagram

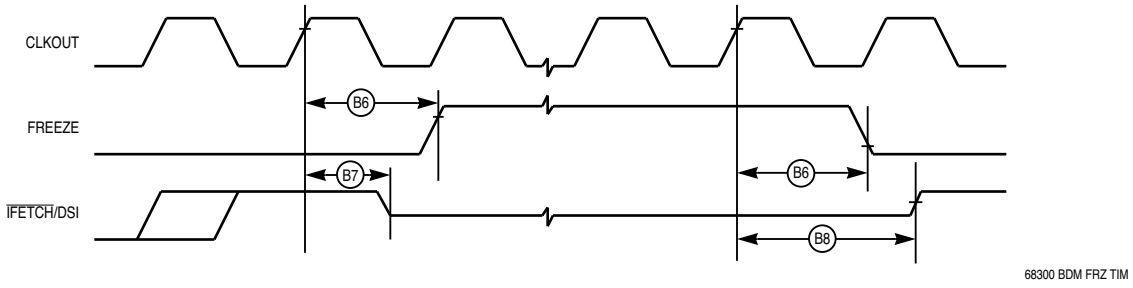


Figure 14 BDM Freeze Assertion Timing Diagram

Table 8 ECLK Bus Timing

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)[1]

Num	Characteristic	Symbol	Min	Max	Unit
E1	ECLK Low to Address Valid[2]	t_{EAD}	—	60	ns
E2	ECLK Low to Address Hold	t_{EAH}	15	—	ns
E3	ECLK Low to $\overline{CS}$ Valid ($\overline{CS}$ Delay)	t_{ECSD}	—	150	ns
E4	ECLK Low to $\overline{CS}$ Hold	t_{ECSH}	15	—	ns
E5	$\overline{CS}$ Negated Width	t_{ECSN}	30	—	ns
E6	Read Data Setup Time	t_{EDSR}	30	—	ns
E7	Read Data Hold Time	t_{EDHR}	5	—	ns
E8	ECLK Low to Data High Impedance	t_{EDHZ}	—	60	ns
E9	$\overline{CS}$ Negated to Data Hold (Read)	t_{ECDH}	0	—	ns
E10	$\overline{CS}$ Negated to Data High Impedance	t_{ECDZ}	—	1	t_{cyc}
E11	ECLK Low to Data Valid (Write)	t_{EDDW}	—	2	t_{cyc}
E12	ECLK Low to Data Hold (Write)	t_{EDHW}	15	—	ns
E13	Address Access Time (Read)[3]	t_{EACC}	386	—	ns
E14	Chip-Select Access Time (Read)[4]	t_{EACS}	296	—	ns
E15	Address Setup Time	t_{EAS}	1/2	—	t_{cyc}

NOTES:
1. All AC timing is shown with respect to 20% V_{DD} and 70% V_{DD} levels unless otherwise noted.
2. When previous bus cycle is not an ECLK cycle, the address may be valid before ECLK goes low.
3. Address access time = $t_{Ecyc} - t_{EAD} - t_{EDSR}$.
4. Chip select access time = $t_{Ecyc} - t_{ECSD} - t_{EDSR}$.

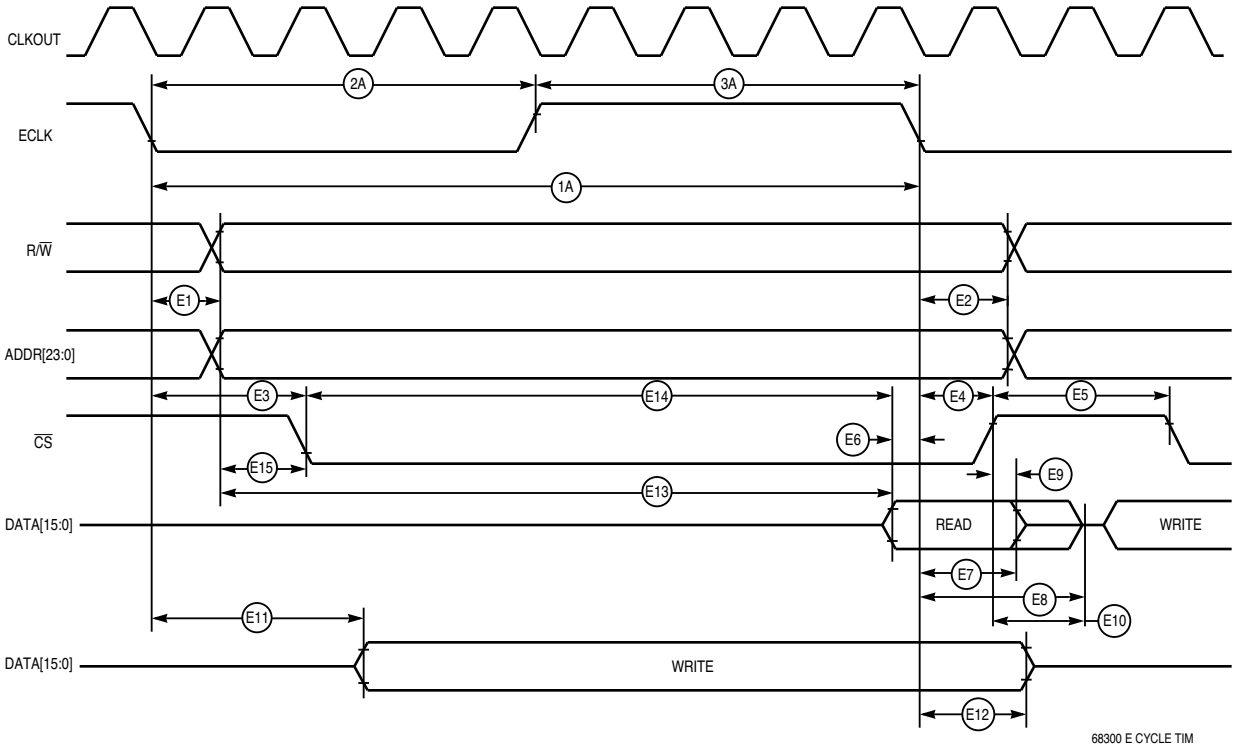


Figure 15 ECLK Timing Diagram

Table 9 QSPI Timing

(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, 100 pF load on all QSPI pins)[1]

Num	Function	Symbol	Min	Max	Unit
1	Operating Frequency Master Slave	f_{op}	DC DC	1/4 1/4	f_{sys} f_{sys}
2	Cycle Time Master Slave	t_{qcyc}	4 4	510 —	t_{cyc} t_{cyc}
3	Enable Lead Time Master Slave	t_{lead}	2 2	128 —	t_{cyc} t_{cyc}
4	Enable Lag Time Master Slave	t_{lag}	— 2	1/2 —	SCK t_{cyc}
5	Clock (SCK) High or Low Time Master Slave[2]	t_{sw}	2 t_{cyc} – 60 2 t_{cyc} – n	255 t_{cyc} —	ns ns
6	Sequential Transfer Delay Master Slave (Does Not Require Deselect)	t_{td}	17 13	8192 —	t_{cyc} t_{cyc}
7	Data Setup Time (Inputs) Master Slave	t_{su}	30 20	— —	ns ns
8	Data Hold Time (Inputs) Master Slave	t_{hi}	0 20	— —	ns ns
9	Slave Access Time	t_a	—	1	t_{cyc}
10	Slave MISO Disable Time	t_{dis}	—	2	t_{cyc}
11	Data Valid (after SCK Edge) Master Slave	t_v	— —	50 50	ns ns
12	Data Hold Time (Outputs) Master Slave	t_{ho}	0 0	— —	ns ns
13	Rise Time Input Output	t_{ri} t_{ro}	— —	2 30	µs ns
14	Fall Time Input Output	t_{fi} t_{fo}	— —	2 30	µs ns

NOTES:
1. All AC timing is shown with respect to 20% V_{DD} and 70% V_{DD} levels unless otherwise noted.
2. For high time, n = External SCK rise time; for low time, n = External SCK fall time.

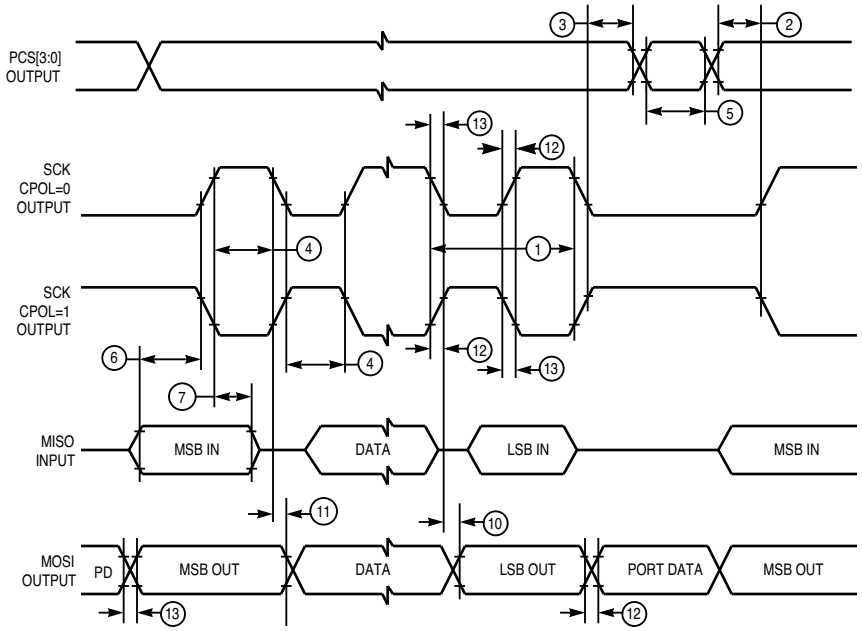


Figure 16 QSPI Timing — Master, CPHA = 0

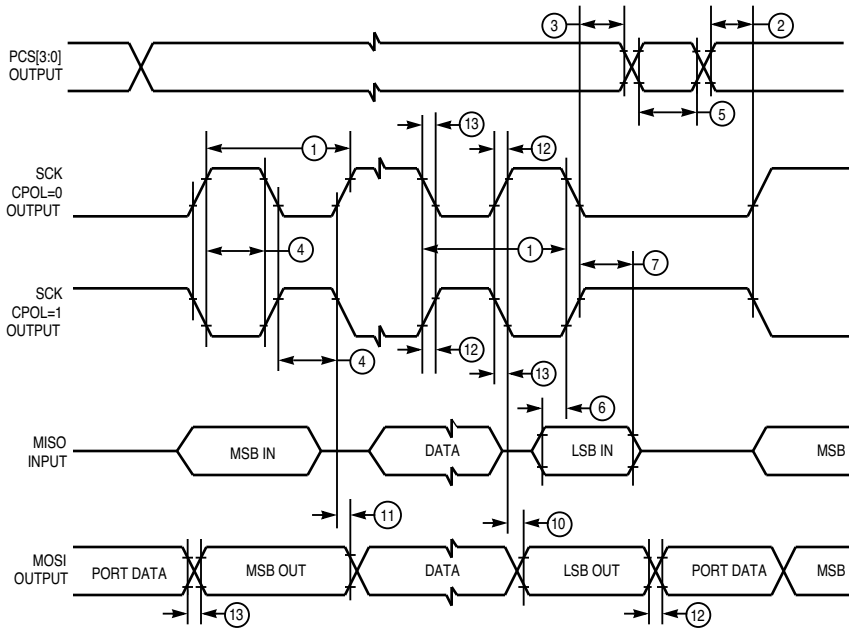


Figure 17 QSPI Timing — Master, CPHA = 1

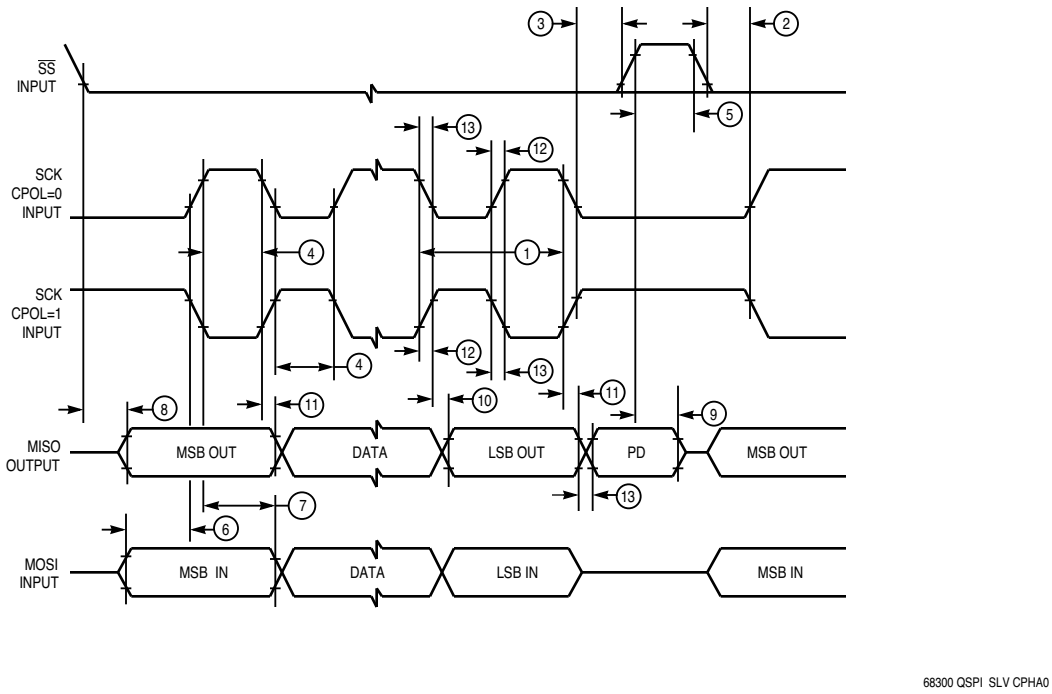


Figure 18 QSPI Timing — Slave, CPHA = 0

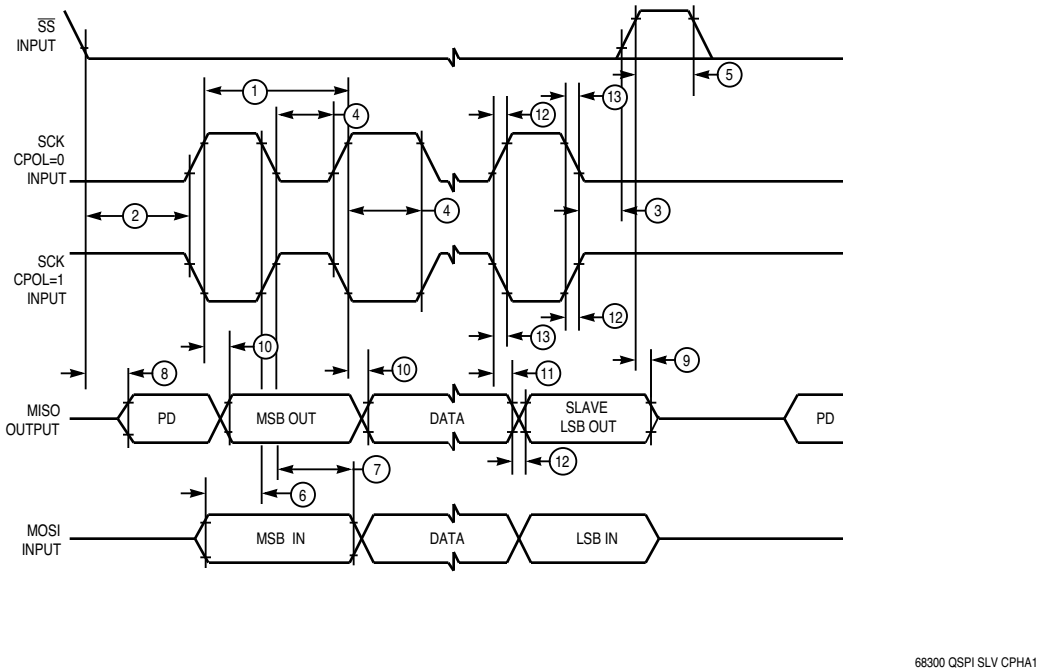


Figure 19 QSPI Timing — Slave, CPHA = 1

Table 10 Time Processor Unit Timing

(V_{DD} and V_{DDA} = 3.0 to 3.6Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H)[1]

Num	Parameter	Symbol	Min	Max	Unit
1	CLKOUT High to TPU Output Channel Valid[2, 3, 4]	t_{CHTOV}	2	23	ns
2	CLKOUT High to TPU Output Channel Hold	t_{CHTOH}	0	20	ns
3	TPU Input Channel Pulse Width	t_{TIPW}	4	—	t_{cyc}

NOTES:
1. AC Timing is shown with respect to 20% V_{DD} and 70% V_{DD} levels.
2. Timing not valid for external T2CLK input.
3. Maximum load capacitance for CLKOUT pin is 90 pF.
4. Maximum load capacitance for TPU output pins is 100 pF.

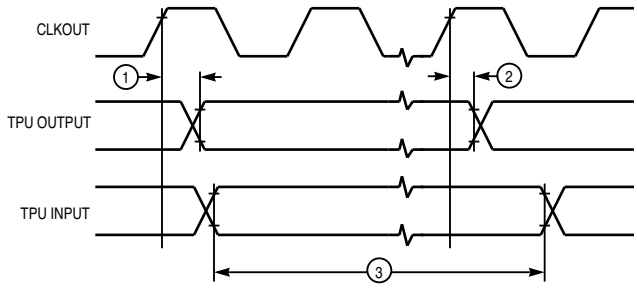


Figure 20 TPU Timing Diagram

Home Page:
www.freescale.com
email:
support@freescale.com
USA/Europe or Locations Not Listed:
Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
(800) 521-6274
480-768-2130
support@freescale.com
Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com
Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku
Tokyo 153-0064, Japan
0120 191014
+81 2666 8080
support.japan@freescale.com
Asia/Pacific:
Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate,
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com
For Literature Requests Only:
Freescale Semiconductor
Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
(800) 441-2447
303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor
@hibbertgroup.com

RoHS-compliant and/or Pb- free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb- free counterparts. For further information, see http://www.freescale.com or contact your Freescale sales representative.

For information on Freescale.s Environmental Products program, go to http://www.freescale.com/epp.

MC68LK332EC16/D